

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	36313	photoresist and etch\$ and (buffer or polymer or etchstop or (etch adj resistance))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 10:30
L3	23623	I2 and oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 10:31
L4	18820	I3 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 10:31
L5	16524	I4 and thickness	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 10:32
L6	9907	I5 and (opening or window)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 10:33
L7	6135	I6 and width	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 10:34
L8	5519	I7 and metal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 10:34
L9	2144	I8 and (dry adj etch\$)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 10:35

L10	30	I9 and ((width adj5 opening) and (photoresist adj5 thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 10:42
L11	609	I9 and aperture	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 11:03
L12	110	I9 and aperture.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/22 11:03